

Digital Media

Code Information

- **MOS**
- **Linear-IC**
- **SIP**

April 2008

MOS Code Information(1/2)

Last Updated : April 2008

S **5** X X X X X X X X - X X X X
 1 2 3 4 5 6 7 8 9 10 11 12 13 14 15

1. System LSI (S)

2. Large Classification : MOS (5)

3. Small Classification

- A : Audio
- B : Analog Core
- C : Camera
- D : Display
- F : CCD
- G : General
- H : Home(Appliance) Video
- I : Digital Core
- K : CIS
- L : Optical
- M : Mobile Automation
- N : Network
- S : SLINK(Serial Link)
- T : Telecom
- V : Process Vehicle
- W : Library
- X : MODULE(CAMERA MODULE)
- Y : Memory Card
- Z : Custom
- 2 : EEPROM
- 4 : DRAM CORE
- 6 : FLASH CORE

4~7.

Serial No

8. Version

A~Z

*1st Version → X

9~10. Mask Option

11. " - "

12. Package Type

- | | |
|-----------|--------------|
| 1 : TEBGA | 2 : MODULE |
| 3 : QFN | 4 : MLF |
| 5 : ELP2 | 6 : WFP |
| 7 : LPCC | 8 : FCBGA |
| 9 : PBGA | A : SDIP |
| B : BGA | C : CHIP BIZ |
| D : DIP | E : LQFP |
| F : BCC++ | G : ELQFP |
| H : ULGA | J : ELP |
| K : SBGA | L : FCFBGA |
| M : QFPH | N : PBGAH |
| P : PLCC | Q : QFP |
| R : TSSOP | S : SOP |
| T : TQFP | U : UELP |
| V : SSOP | W : WAFER |
| X : ETQFP | Y : FBGA |
| Z : STBGA | |

13. Reserved

- | | |
|------------------|------------------|
| 0 : none | 1 : PKG Option 1 |
| 2 : PKG Option 2 | 3 : PKG Option 3 |
| | |
| G : PKG Option G | H : PKG Option H |

14. Packing

- | | |
|------------------------------------|-----------------|
| B : Tube | U : Bulk |
| R : Tray | T : Tape & Reel |
| S : Tape & Reel Reverse | C : Chip Biz |
| D : Chip Biz (3 Inch tray) | |
| E : Chip Biz (4 Inch tray) | |
| F : Chip Biz (Reverse) | |
| W : WF Biz Draft Wafer | |
| X : WF Biz Full Cutting | |
| 3 : Tape & Reel (Halogen-Free PKG) | |
| 4 : Tray (Halogen-Free PKG) | |
| 5 : Tube (Halogen-Free PKG) | |
| 7 : Tape & Reel (Lead-Free PKG) | |
| 8 : Tray (Lead-Free PKG) | |
| 9 : Tube (Lead-Free PKG) | |

MOS Code Information(2/2)

Last Updated : April 2008

<u>S</u>	<u>5</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	-	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>
1	2	3	4	5	6	7	8	9	10	11	12	13	14	15

15. Customer

- 0 : None
- 1 : Bonding Option 1
- 2 : Bonding Option 2
- 3 : Bonding Option 3
- 4 : Bonding Option 4
- 5 : Bonding Option 5
- 6 : Bonding Option 6
- 7 : Bonding Option 7
- 8 : Bonding Option 8
- 9 : Bonding Option 9
- A : Special Marking 1
- B : Special Marking 2
- C : Special Marking 3
- D : Special Marking 4
- E : Special Marking 5
- F : Special Marking 6
- K : Reliability Test
- L : No Logo
- M : No Marking
- N : ANAM Assembly
- Q : Bonding Option 10
- R : Bonding Option 11
- S : Bonding Option 12
- T : Bonding Option 13
- U : Bonding Option 14
- Z : Customer Option

L(Linear)-IC Code Information

Last Updated : April 2008

S **1** X X X X X X X X - X X X X
 1 2 3 4 5 6 7 8 9 10 11 12 13 14 15

1. System LSI (S)

2. Large Classification : L-IC (1)

3. Small Classification

- A : Analog Audio
- C : Camera
- D : Display
- G : General
- H : Home(Appliance) Video
- L : Optical
- M : Mobile Communication
- N : Network
- P : PC Peripheral
- S : Smart Power
- T : Telecom
- V : Processor Vehicle
- Z : Custom

4~7.

Serial No

8. Version

A~Z

*1st Version → X

9~10. Mask Option

11. " - "

12. Package Type

- | | |
|-----------|-----------|
| 2 : LPCC | 3 : SOPH |
| A : SDIP | B : BCC+ |
| D : DIP | E : LQFP |
| F : BCC | G : CLCC |
| H : DIPH | I : SIP |
| J : ELP2 | M : MLF |
| N : QFN | P : ELP |
| Q : QFP | R : TSSOP |
| S : SOP | T : TQFP |
| V : SSOP | W : WAFER |
| X : SIPH | Y : FBGA |
| Z : BCC++ | |

13. Reserved

- Bin Grade

- 0 : None or Root Product
- A : 1st derivative Product
- B : 2nd derivative Product

- PKG Option

- 1 : PKG Option 1
- 2 : PKG Option 2
- 3 : PKG Option 3

14. Packing

- | | |
|------------------------------------|-----------------|
| B : Tube | U : Bulk |
| R : Tray | T : Tape & Reel |
| S : Tape & Reel Reverse | C : Chip Biz |
| D : Chip Biz (3 Inch tray) | |
| E : Chip Biz (4 Inch tray) | |
| F : Chip Biz (Reverse) | |
| W : WF Biz Draft Wafer | |
| X : WF Biz Full Cutting | |
| 3 : Tape & Reel (Halogen-Free PKG) | |
| 4 : Tray (Halogen-Free PKG) | |
| 5 : Tube (Halogen-Free PKG) | |
| 7 : Tape & Reel (Lead-Free PKG) | |
| 8 : Tray (Lead-Free PKG) | |
| 9 : Tube (Lead-Free PKG) | |

15. Customer

- | | |
|-----------------------|-----------------------|
| 0 : None | 2 : Bonding Option 2 |
| 1 : Bonding Option 1 | 4 : Bonding Option 4 |
| 3 : Bonding Option 3 | 6 : Bonding Option 6 |
| 5 : Bonding Option 5 | 8 : Bonding Option 8 |
| 7 : Bonding Option 7 | A : Special Marking 1 |
| 9 : Bonding Option 9 | C : Special Marking 3 |
| B : Special Marking 2 | E : Special Marking 5 |
| D : Special Marking 4 | K : Reliability Test |
| F : Special Marking 6 | M : No Marking |
| L : No Logo | Q : Bonding Option 10 |
| N : ANAM Assembly | S : Bonding Option 12 |
| R : Bonding Option 11 | U : Bonding Option 14 |
| T : Bonding Option 13 | |
| Z : Customer Option | |

SIP II Code Information

Last Updated : April 2008

S **B** X X X X X X X X - X X X X
1 2 3 4 5 6 7 8 9 10 11 12 13 14 15

1. System LSI (S)

2. Large Classification : SIP II (B)

In the case of SIP products including of S4/S7 products

3. Small Classification

4 : ASIC

4~7.

Serial No

8. Version

A~Z

*1st Version → X

9~10. Mask Option

11. " - "

12. Package Type (AG01000 is standard)

A : BGAH

E : LQFP

Y : FBGA

U : LGA

13. Reserved

0 : The Final assembly

1 : Initial assembly

2 : Second assembly

14. Packing

B : Tube

U : Bulk

R : Tray

T : Tape & Reel

S : Tape & Reel Reverse

C : Chip Biz

D : Chip Biz (3 Inch tray)

E : Chip Biz (4 Inch tray)

F : Chip Biz (Reverse)

W : WF Biz Draft Wafer

X : WF Biz Full Cutting

3 : Tape & Reel (Halogen-Free PKG)

4 : Tray (Halogen-Free PKG)

5 : Tube (Halogen-Free PKG)

7 : Tape & Reel (Lead-Free PKG)

8 : Tray (Lead-Free PKG)

9 : Tube (Lead-Free PKG)

15. Reserved

0 : Reserved